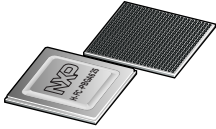


# SOT2295-1

H-FC-PBGA625, thermal enhanced - flip chip - plastic ball grid array, 625 terminals, 0.65 mm pitch, 17 mm x 17 mm x 1.446 mm body

17 April 2026

Package information



## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	H-FC-PBGA625
<b>Package style descriptive code</b>	H-FC-PBGA (thermal enhanced - flip chip - plastic ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-07-2025
<b>Manufacturer package code</b>	98ASA02278D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	16.925	17	17.075	mm
package width	16.925	17	17.075	mm
seated height	1.354	1.446	1.54	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	625	-	





H-FC-PBGA625, thermal enhanced - flip chip - plastic ball grid array, 625 terminals, 0.65 mm pitch,  
17 mm x 17 mm x 1.446 mm body

3 Notes

H-FC-PBGA-625 I/O, LIDDED  
17 X 17 X 1.446 PKG, 0.65 PITCH

SOT2295-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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DATE: 22 JUL 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02278D	REVISION: 0	
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Figure 2. Package outline note H-FC-PBGA625 (SOT2295-1)

H-FC-PBGA625, thermal enhanced - flip chip - plastic ball grid array, 625 terminals, 0.65 mm pitch,  
17 mm x 17 mm x 1.446 mm body

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H-FC-PBGA625, thermal enhanced - flip chip - plastic ball grid array, 625 terminals, 0.65 mm pitch,  
17 mm x 17 mm x 1.446 mm body

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